



## IPC International Conference Call for Papers

**May 5-7, 2009 - San Jose Fairmont  
San Jose, California**

IPC, a global trade association representing the electronics assembly and printed circuit board supply chains, is sponsoring a conference devoted to the exchange of information on leading edge electronic materials.

Electronic materials are a key technology for future success in the electronics manufacturing industry. Lead-free technology, higher assembly temperatures, higher data rates and smaller form factors are just a few of the issues leading to a focus on materials, their capabilities, their limitations and their future.

To support the development of next generation materials for electronics technology and assembly IPC is inviting all relevant stakeholders to this first IPC Materials Conference. Companies and academic institutions worldwide are invited to submit an abstract to share information on new research, applications and solutions in the area of electronic materials

**Submissions for papers are sought on all materials topics associated with PCB fabrication and design, assembly processes, green technology including:**

- Device Packaging
- Black Pad
- Design
- Lead Free & Tin Whiskers
- Halogen Free
- REACH and RoHS
- Embedded Passive & Active Devices
- Environmental Compliance
- Flexible Circuitry
- HDI Technologies
- High Speed, High Frequency Materials and their Design Impact
- Optoelectronics
- Packaging & Components
- PCB Fabrication
- Surface Finish
- Performance, Quality & Reliability
- Printed Electronics
- Rework & Repair
- Soldering
- Surface Finishes
- Via Plugging

### **REQUIREMENTS FOR SUBMISSION**

Provide an abstract of approximately 300 words that summarizes technical and **previously unpublished, noncommercial** work covering case histories, research and discoveries. It must be received by **December 15, 2008**. Authors will be notified by **January 26, 2009**. A complete paper is required for presentation by **April 7, 2009**.

For more information about conference participation, please contact **Greg Munie**, Conference Director, at [GregMunie@ipc.org](mailto:GregMunie@ipc.org) or **Michelle Michelotti**, at [MichelleMichelotti@ipc.org](mailto:MichelleMichelotti@ipc.org) or at +1 847-597-2822.

### **EDUCATIONAL COURSES**

Proposals are also solicited from individuals interested in teaching half-day workshops (three hours) to a class of up to 30 persons on topics in the field. Examples include: device packaging, black pad, design, lead free & tin whiskers, halogen free, REACH and RoHS etc. Additional suggestions are also welcome.

An honorarium is offered to workshop instructors. A brief description and additional information on any such proposals should be submitted according to the guidelines for abstract submission i.e. by completion of the attached form.

### **SPONSORSHIPS AND TABLETOP EXHIBITS**

Companies interested in information on the benefits associated with IPC event sponsorship or exhibiting in our tabletop exhibit, please email [MichelleMichelotti@ipc.org](mailto:MichelleMichelotti@ipc.org).

### **REGISTRATION INFORMATION**

If you would like to receive registration information on one of the IPC Materials Conference when available, please send your contact information to [MichelleMichelotti@ipc.org](mailto:MichelleMichelotti@ipc.org).

## **ABSTRACT AND PROPOSAL INSTRUCTIONS**

**Complete and mail, fax or e-mail this form with your biography and abstract/course descriptions to:**

Attention: **Materials Conference**

IPC – Association Connecting Electronics Industries

3000 Lakeside Drive, Suite 309 S

Bannockburn, IL 60015 - USA

Phone: (847) 597-2822 Fax: (847) 615-5622 / E-mail: [MichelleMichelotti@ipc.org](mailto:MichelleMichelotti@ipc.org)

Name \_\_\_\_\_

Company \_\_\_\_\_ Title \_\_\_\_\_

Street Address \_\_\_\_\_

City \_\_\_\_\_ State/Zip Code/Country \_\_\_\_\_

Phone \_\_\_\_\_ Fax \_\_\_\_\_

E-mail \_\_\_\_\_

**Presentation Slot Desired:**  30 minutes  45 minutes

On a separate page, please include your 200-300-word **abstract** describing the presentation you wish to have considered for the Materials Conference.

**Workshop**

On a separate page, please include your **course description** you wish to have considered for the Materials Conference.

**Indicate the general area of Technology:**

- |  |  |
|--|--|
| <ul style="list-style-type: none"><li><input type="radio"/> Device Packaging</li><li><input type="radio"/> Black Pad</li><li><input type="radio"/> Design</li><li><input type="radio"/> Lead Free &amp; Tin Whiskers</li><li><input type="radio"/> Halogen Free</li><li><input type="radio"/> REACH and RoHS</li><li><input type="radio"/> Embedded Passive &amp; Active Devices</li><li><input type="radio"/> Environmental Compliance</li><li><input type="radio"/> Flexible Circuitry</li><li><input type="radio"/> HDI Technologies</li><li><input type="radio"/> High Speed, High Frequency Materials and their Design Impact</li></ul> | <ul style="list-style-type: none"><li><input type="radio"/> Optoelectronics</li><li><input type="radio"/> Packaging &amp; Components</li><li><input type="radio"/> PCB Fabrication</li><li><input type="radio"/> Surface Finish</li><li><input type="radio"/> Performance, Quality &amp; Reliability</li><li><input type="radio"/> Printed Electronics</li><li><input type="radio"/> Rework &amp; Repair</li><li><input type="radio"/> Soldering</li><li><input type="radio"/> Surface Finishes</li><li><input type="radio"/> Via Plugging</li></ul> |
|--|--|

Other \_\_\_\_\_

Has this paper or course been presented before?  Yes  No

If yes, when and where? \_\_\_\_\_